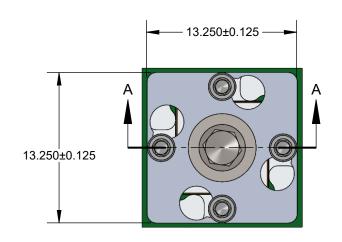
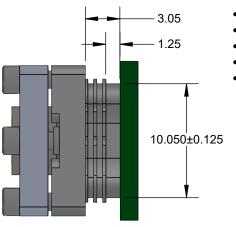
# GHz BGA Socket - Epoxy mount, solderless

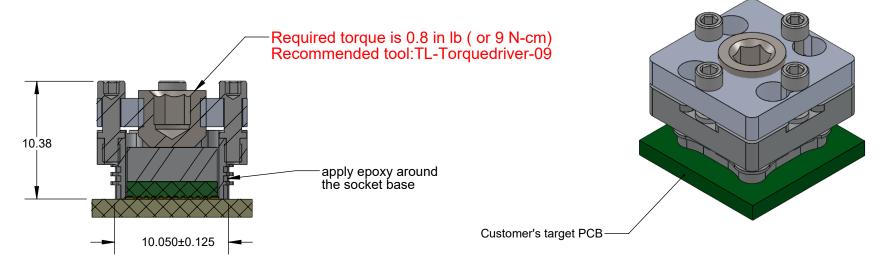




#### **Features**

- Directly mounts to target PCB. High speed, reliable Elastomer connection Minimum real estate required Compression plate distributes forces evenly Easily removable socket lid

#### **TOP VIEW**



#### **SECTION A-A**

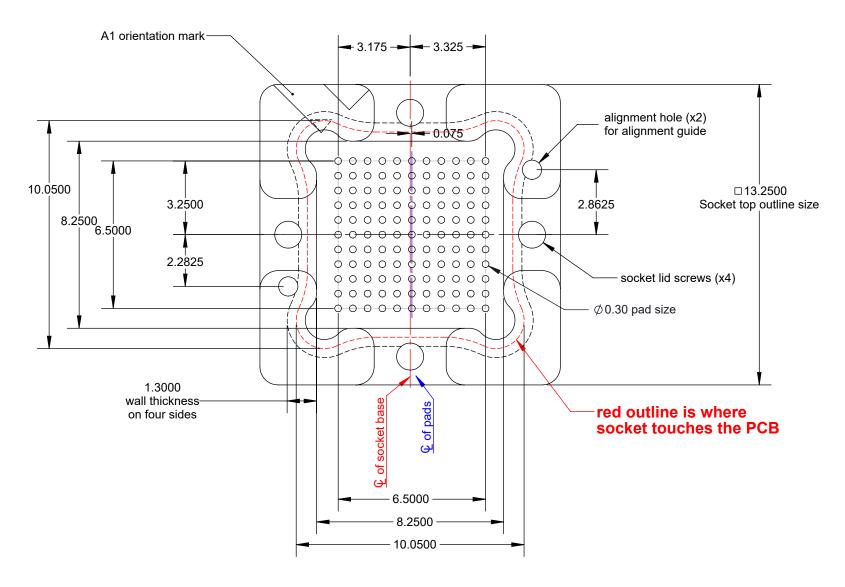
### Description: Epoxy Mount Socket for 8x8mm 11x11 0.65mm pitch BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SG15-BGA-1004 Drawing	Material: N/A	STATUS: Released	SHEET: 1 OF 5	REV. A
•	Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: N/A Weight: 4.12	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:1
	www.ironwoodelectronics.com	Weight: 4.12	FILE: SG15-BGA-1004 Dwg	DATE: 09/14/2016	

\*Note: BGA pattern is not symmetrical with respect to the socket outline. It is shifted by 0.075mm to the right.



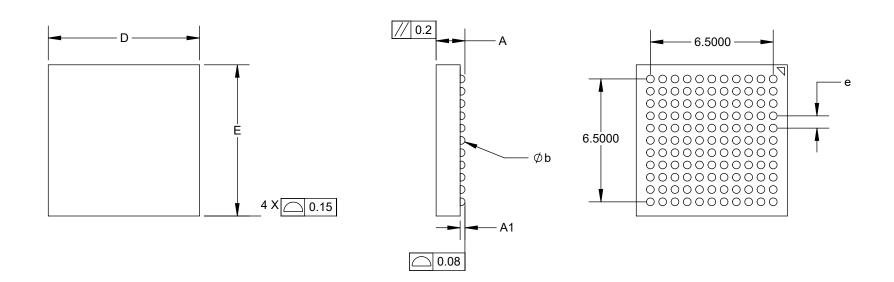
### **Description: Recommended PCB Layout**

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SG15-BGA-1004 Drawing	Material: N/A	STATUS: Released	SHEET: 2 OF 5	REV. A
6	10.0. (000) 10. 020.	Finish: N/A Weight: 4.12	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 6:1
			FILE: SG15-BGA-1004 Dwg	DATE: 09/14/2016	

## Ironwood Package Code: BGA121F



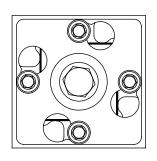
DIM	Minimum	Maximum	
Α		1.52	
A1	0.15	0.25	
b	0.25	0.35	
D	8.00 BSC		
E	8.00 BSC		
е	0.65 BSC		
ARRAY	11x11		
PIN COUNT		121	

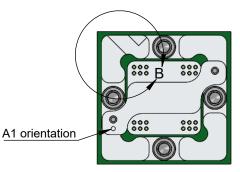
### **Description: Compatible BGA IC**

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

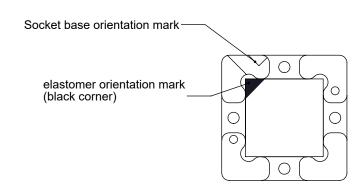
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

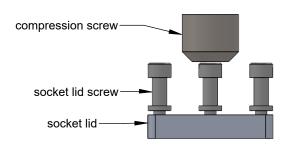
SG15-BGA-1004 Drawing	Material: N/A	STATUS: Released	SHEET: 3 OF 5	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: N/A Weight: 4.12	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 5:1
www.ironwoodelectronics.com	Weight. 4.12	FILE: SG15-BGA-1004 Dwg	DATE: 09/14/2016	





Top View Alignment Guide

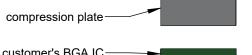


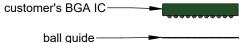




DETAIL B SCALE 3.5 : 1

When elastomer orientation mark is on upper left corner, side view of elastomer should be









# **User Instructions:**

For socket mounting instructions refer EPM (Epoxy socket user manual)

http://www.ironwoodelectronics.com/catalog/content/drawings/epm.pdf

Description: User Instructions

Primary dimension units are millimeters, Secondary dimension units are [inches], Weightstormer's target PCB

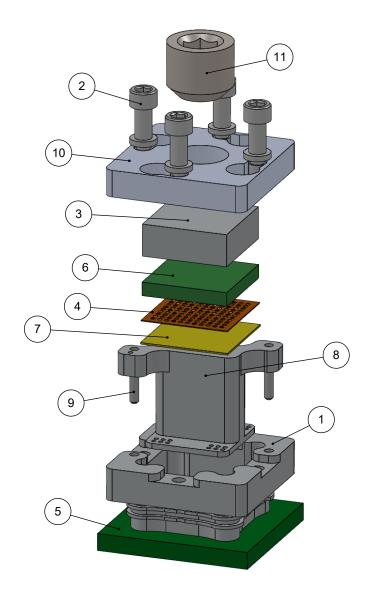
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

#### SG15-BGA-1004 Drawing



Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: N/A Finish: N/A Weight: 4.12 epoxy area

STATUS: Released	SHEET: 4 OF 5	REV. A
ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 2.5:1
FILE: SG15-BGA-1004 Dwg	DATE: 09/14/2016	



ITEM NO.	DESCRIPTION	Material
1	Epoxy Socket Base 8x8mm IC	7075-T6 Aluminum Alloy
2	#0-80 Shoulder Screw, 1.59mm thread length	Stainless Steel (303)
3	Compression Plate 3mm TK	7075-T6 Alumium Alloy
4	Ball guide 11x11 array 0.65mm pitch	Kapton Polyimide
5	Target PCB 11x11 array 0.65mm pitch	FR4 Standard
6	Customer's BGA device	FR4 High temp
7	0.15mm thick, 0.05x 0.05mm pitch, 10mm sqr, Z-axis conductive angled elastomer	20 Micron dia gold plated brass filaments arranged symettrically in a silicon rubber (63.5 degree angle), Thickness: 0.5mm
8	epoxy mount alignment guide	7075-T6 Aluminum Alloy
9	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel
10	Socket lid for 8x8mm IC	7075-T6 Aluminum Alloy
11	Compression Screw M6x1	Stainless Steel (18-8)

## **Description: Material info**

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

### SG15-BGA-1004 Drawing



Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: N/A Finish: N/A Weight: 4.12

STATUS: Released	SHEET: 5 OF 5	REV. A
ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:1
FILE: SG15-BGA-1004 Dwg	DATE: 09/14/2016	